

IN THE SPECIFICATION

On page 2 first line please insert -- This is a Divisional Application of Serial No.: 10/062,255 filed January 31, 2002, which is presently pending. --

IN THE CLAIMS

Please cancel claims 1-15 and 31-41 without prejudice.

Please add new claims 27-30

27. (New) A system comprising:

a printed circuit board; and
an integrated circuit package mounted on the printed circuit board, the integrated circuit package comprising an integrated circuit, an integrated heat spreader thermally coupled to a backside surface of the integrated circuit, and a thermal interface material disposed between the backside surface of the integrated circuit and a bottom surface of the integrated heat spreader, the thermal interface material covalently bonded to the bottom surface of the integrated heat spreader and/or the backside surface of the integrated circuit.

28. (New) The system of claim 27, wherein the thermal interface material has a thermal conductivity greater than 4 W/mK.

29. (New) The systems of claim 27, wherein the thermal interface material comprises an epoxy resin covalently bonded to the backside surface of the integrated circuit.

30. (New) The system of claim 27, wherein the integrated circuit package is a control collapse chip connection (C4) package.

If there are any additional charges, please charge Deposit Account No. 02-2666.

Respectfully submitted,

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